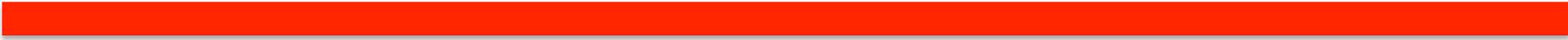


# Atlas R&D Activities



## **Simulations, Sensors, Electronics & Mechanics**

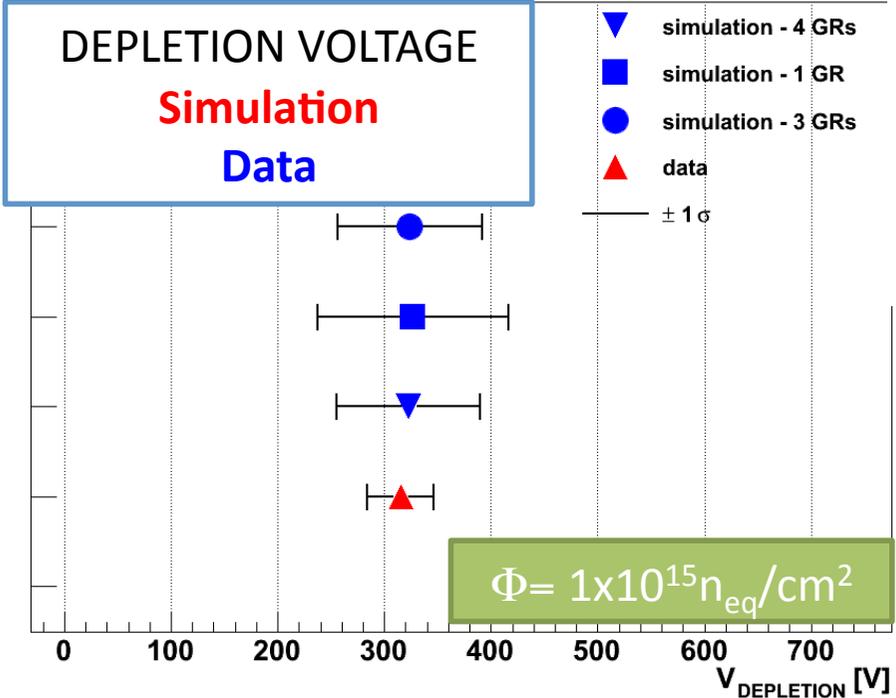
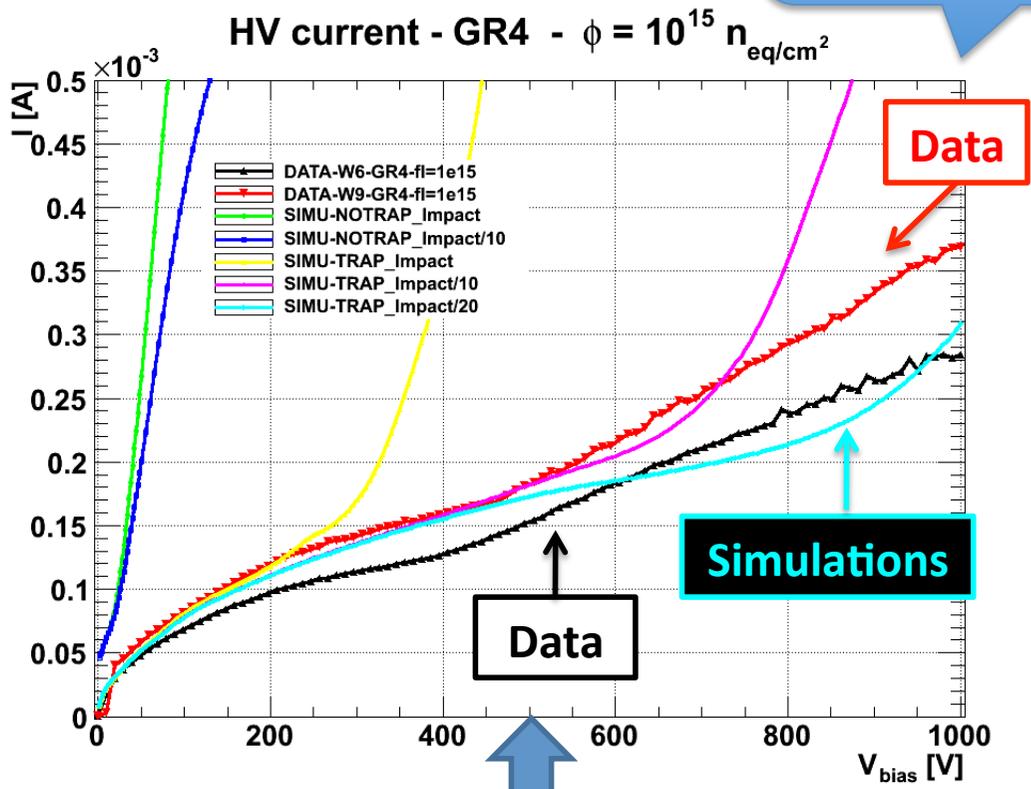
Didier, Filipe, Francesco, Giovanni & Giovanni,  
Jacques, Jean-François, Marco & Olivier

# TCAD Simulations of irradiated sensors

Presented at 21<sup>st</sup> RD50 WS



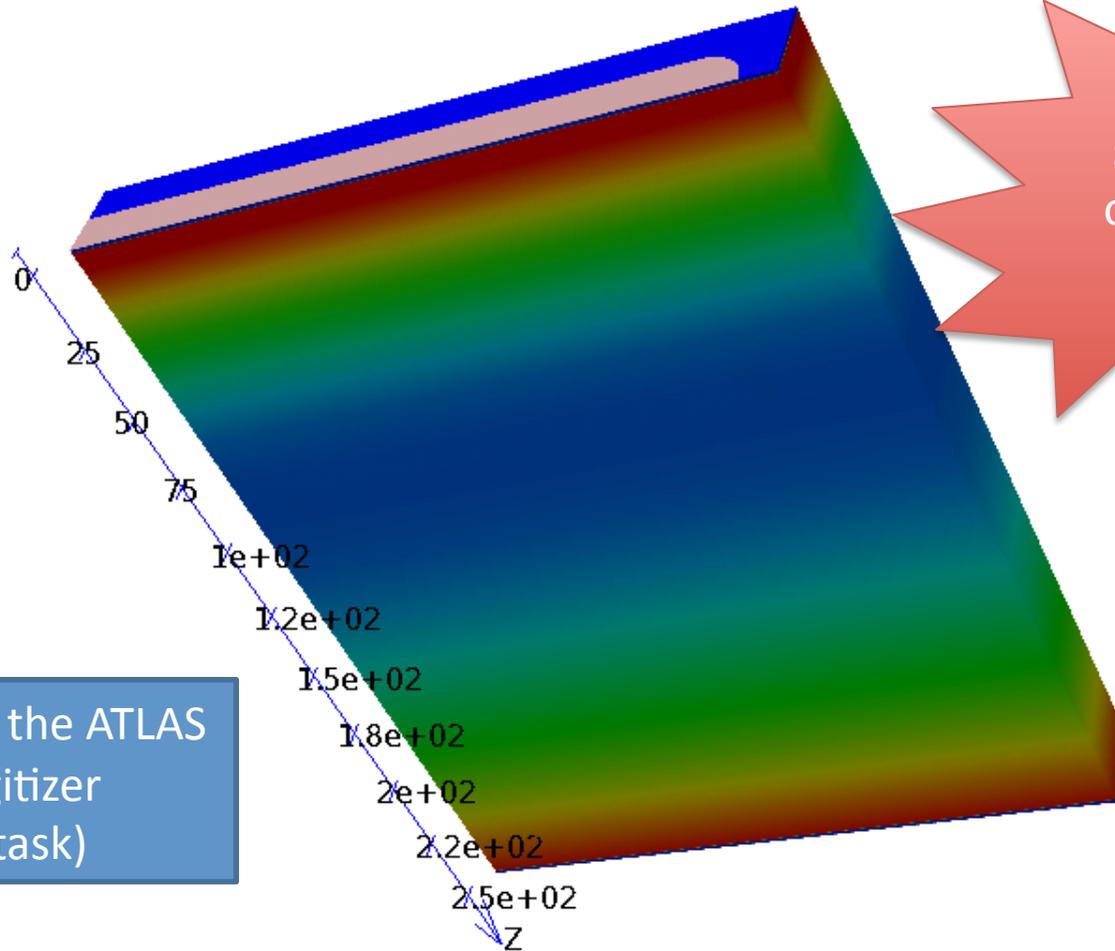
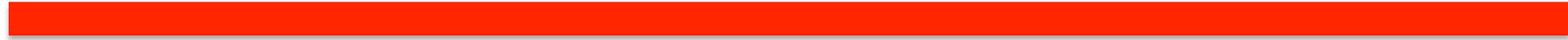
Irradiated (and annealed) n-on-p diodes



A lot of work for impact ionization models and interface traps and charges

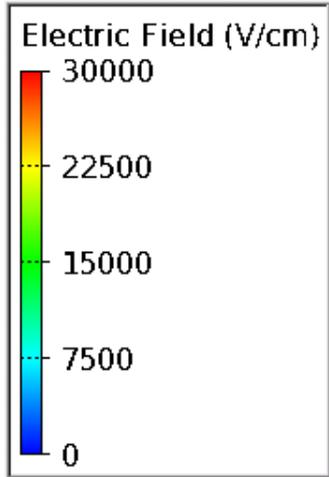
Model for irradiated P-bulk sensors validated on data

# New: 3D simulations

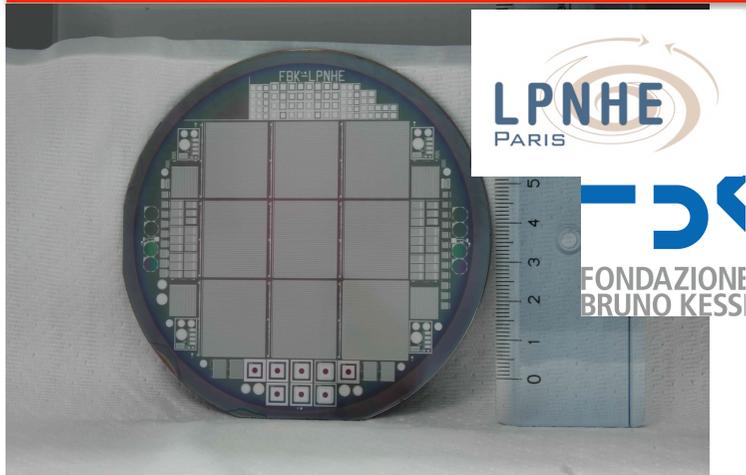


NEW! 3D simulations of irradiated sensors

To be used for the ATLAS pixels digitizer (official task)

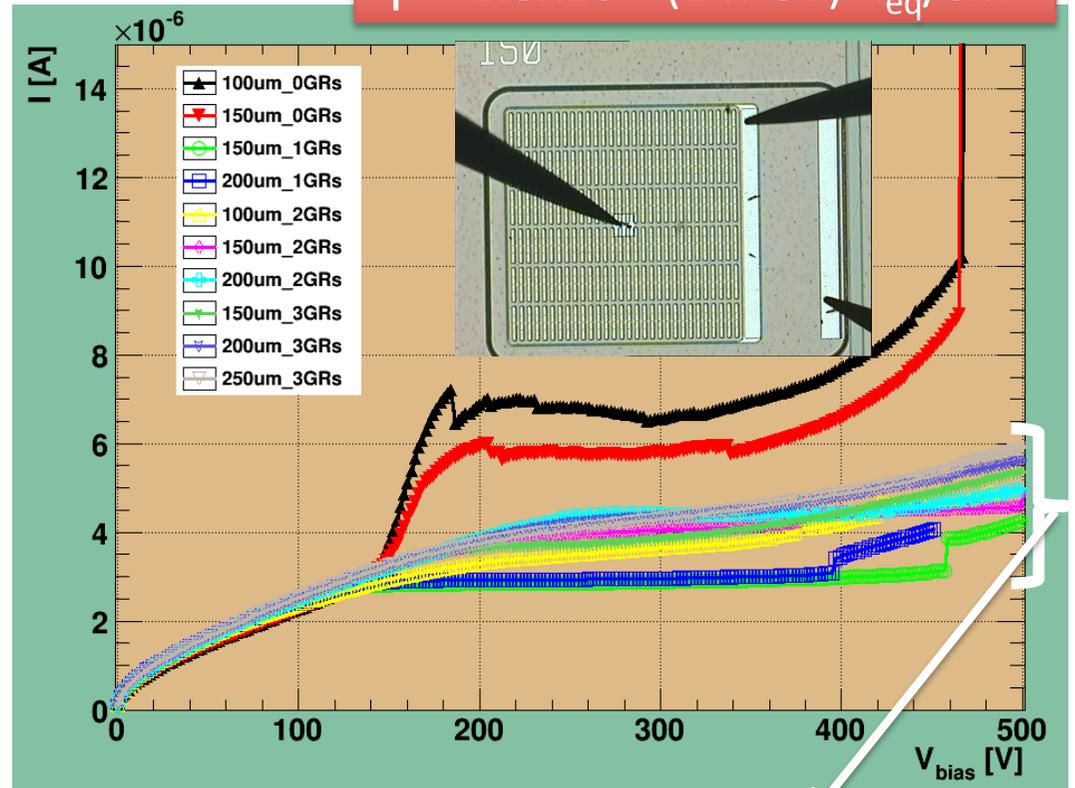


# Edgeless sensors for the Phase-II Atlas Pixels

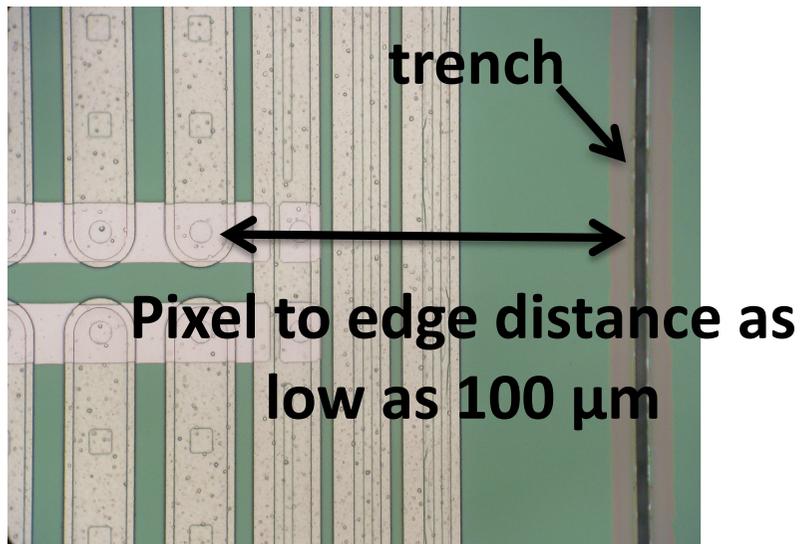


Performance after irradiation presented at IEEE 2013

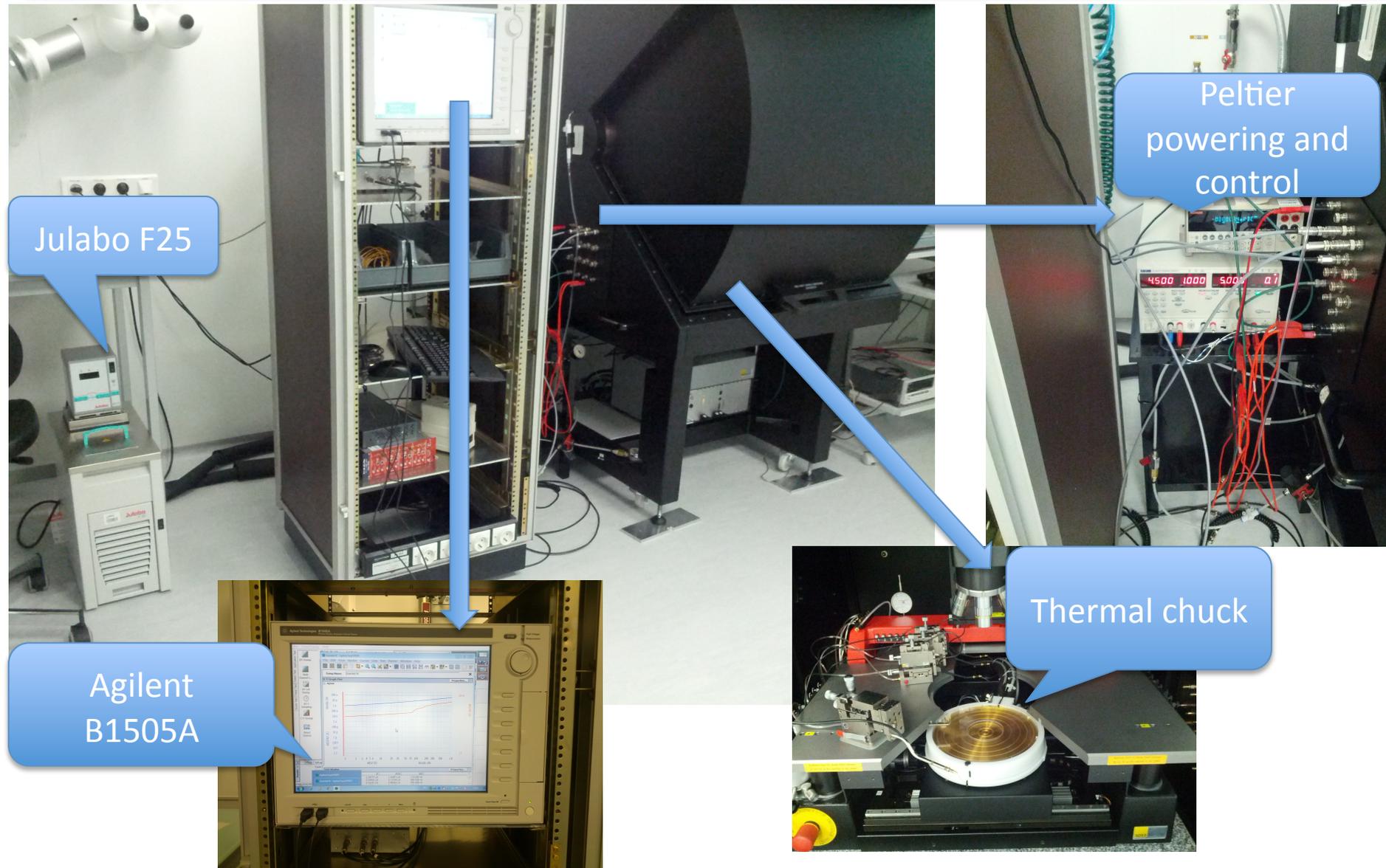
$$\phi = 2.5 \times 10^{15} (1 \text{ MeV}) n_{eq}/\text{cm}^2$$



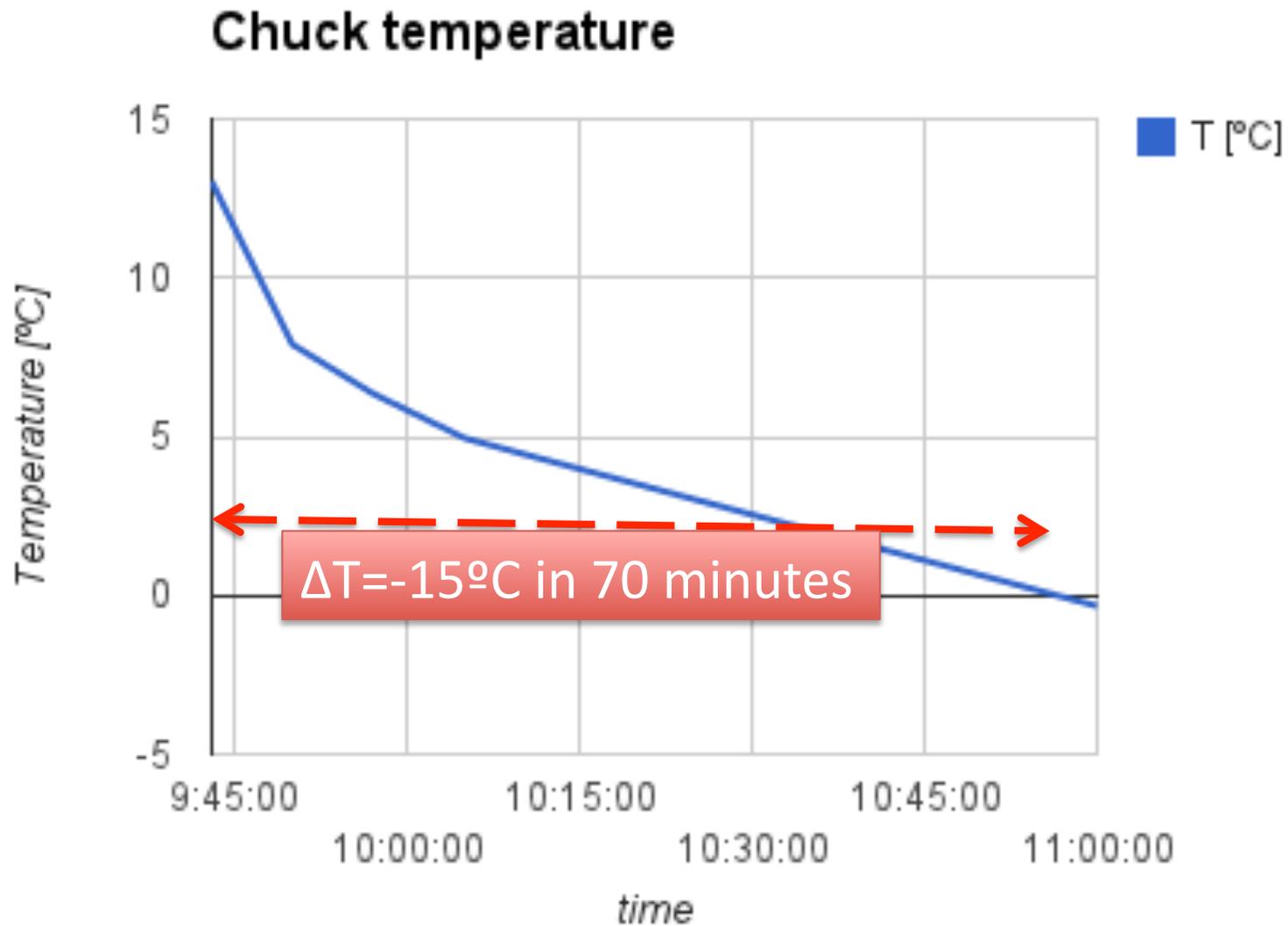
≥ 1 GR: very stable!



# Cold setup in our cleanroom

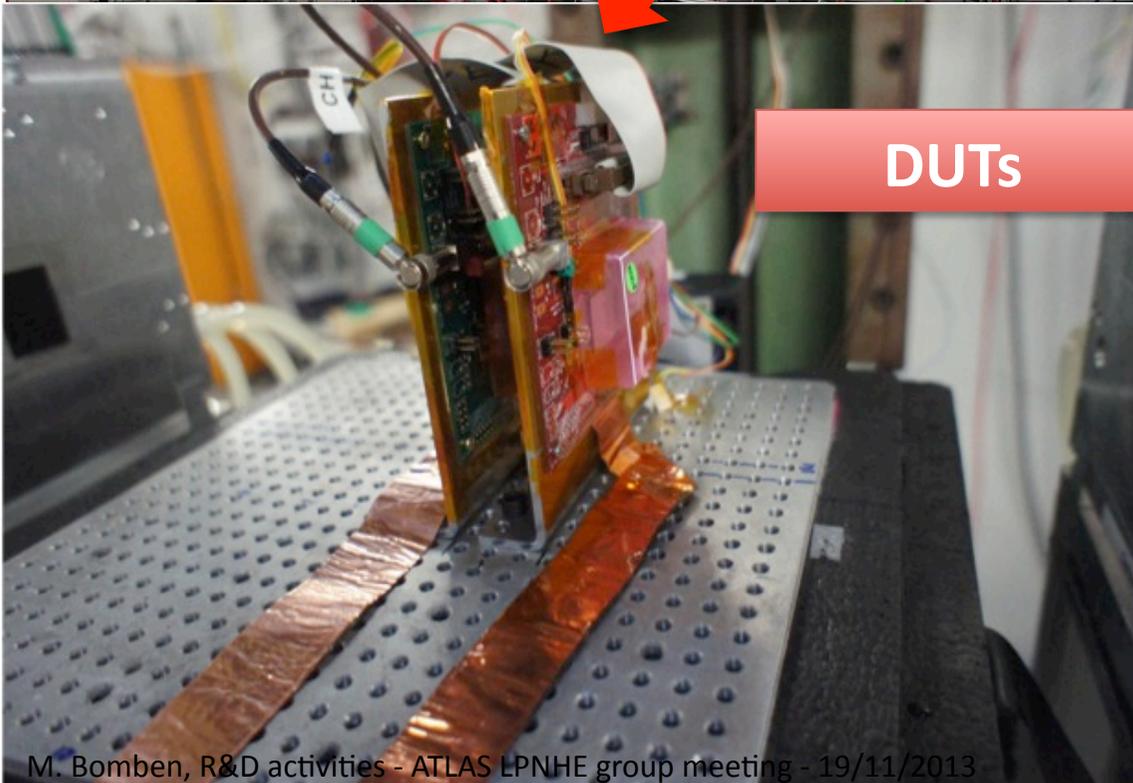
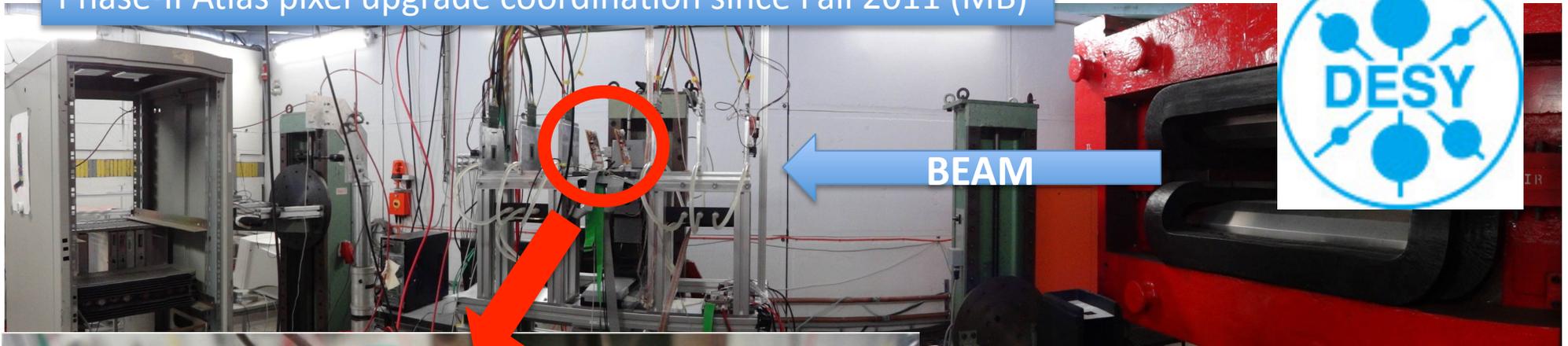


# Cold chuck performance



# Beam test setup (DESY)

Phase-II Atlas pixel upgrade coordination since Fall 2011 (MB)



- Spring, Summer and Fall beam test campaigns at DESY with 4 GeV/c electrons
- Total: > 10 weeks
  - Reminder: No beam at CERN till late 2014
- Phase-II pixel candidates tested

# Beam test highlights

Phase-II Atlas pixel upgrade coordination since Fall 2011 (MB)

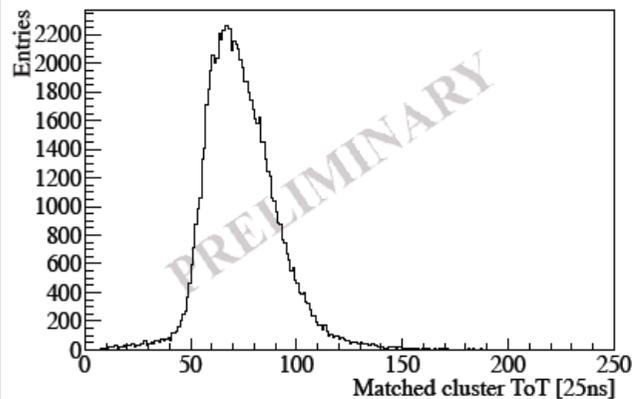
Characterization of thin n-in-p planar pixel sensors with active edges before and after irradiation

n-in-p FE-I4 pixel modules 150  $\mu\text{m}$  thick

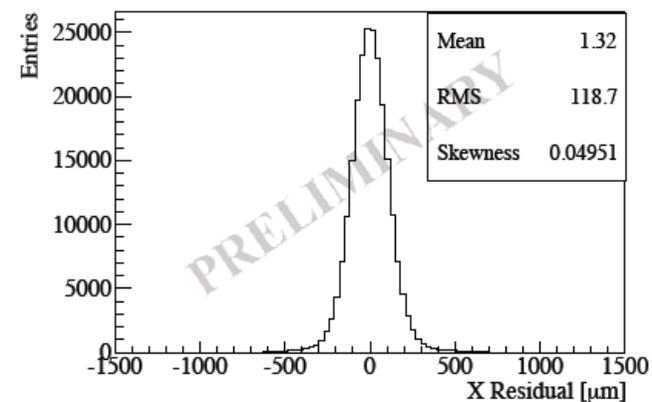
## Pixel cell efficiency: high-eta

- ▶ FE-I4 150  $\mu\text{m}$  thick, irradiated to  $4 \times 10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$  in Los Alamos
- ▶  $\vartheta=85^\circ$  track incidence ( $\eta \sim 3.1$ )

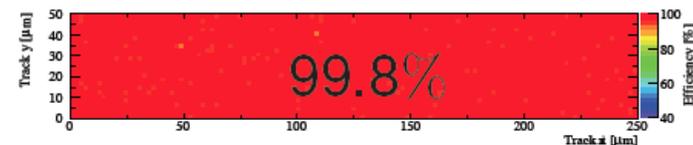
Full cluster ToT distribution  
as expected (10 ToT@10 ke)



Residual along the titled  
direction (pitch: 250  $\mu\text{m}$ )



99.8% hit efficiency  
for matched clusters



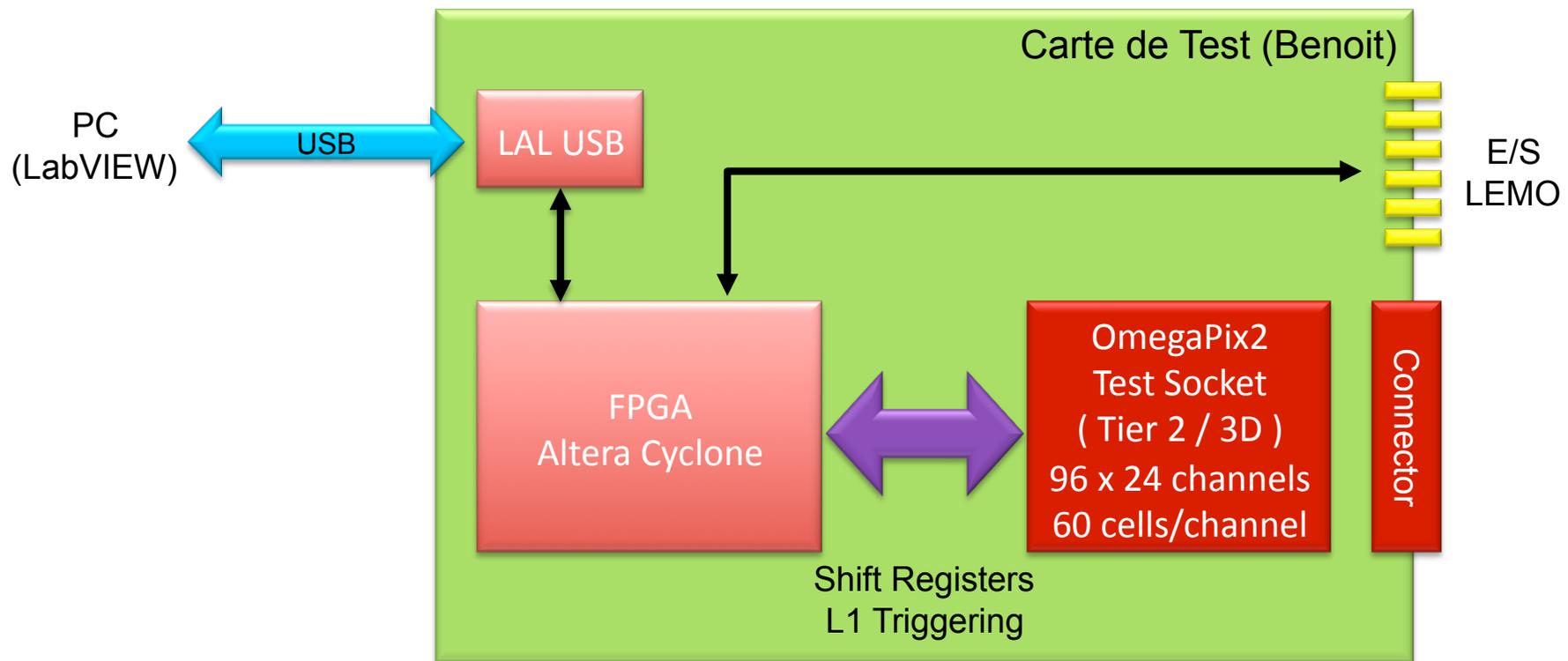
# Omegapix2 status

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- The Omega group has received a set of packaged Omegapix2 **digital** tier chips in the end of september.
- Tests in Paris began on tuesday 8th oct (visit of Damien and Jeanne from Omega, M. Cohen-Solal and C. Sylvia from LAL): power up, setting up of the various test boards ( one board per lab is now operational )
- Olivier made some fpga firmware and labview software adjustments last week:  
=> **good programming** of the various shift registers of the digital chip
- **The setup is now ready to test the pipelining and L1 triggering logic.** Olivier will continue the tests.
- On the other hand, **the 3D version** (analog + digital tier) is now **\*really\* expected soon**

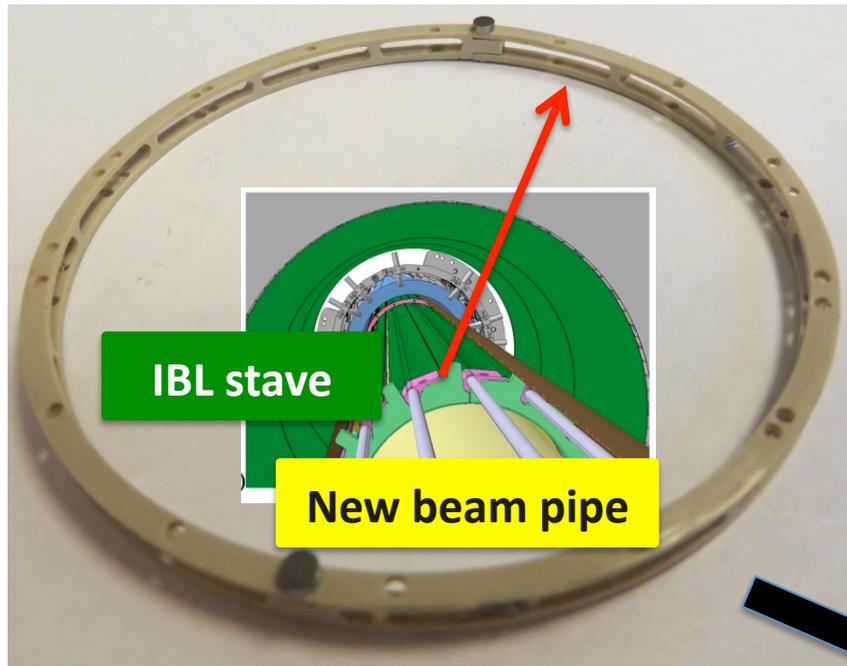
# Banc de test Omegapix2 3D

- Carte de test Omegapix2 3D
  - Circuit: Omegapix2 Tier Numérique et version 3D



# IBL central ring (100% Made in LPNHE)

- 2 pièces → 7 Pièces



- Matière : PEEK
- → PAI (Polyamide-imide)

# Conclusions

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- TCAD simulations results: an effort recognized by the ATLAS (and not only) community
- FBK-LPNHE Edgeless sensors: good electrical performance, even after irradiation
- Beam test: a lot of measurements done; nice results from important HL-LHC scenarios
- Electronics: LAL/LPNHE synergy for 3D/65nm chip
- Mechanics: good impact of LPNHE work on IBL